

CHIP-ON-FILM USE COPPER FOILABSTRACT OF THE DISCLOSURE

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A copper foil having a high etching factor, enabling formation of fine patterns excellent in linearity of bottom lines of circuit patterns and without leaving particles of copper foil forming the circuit patterns in 10 the resin, free from a drop in bond strength between the copper foil and resin substrate due to the processing for formation of solder balls, excellent in visibility, and excellent in mounting of ICs on fine patterns, comprising a copper foil on at least one surface of which is 15 provided an alloy fine roughening particle layer comprised of a copper-cobalt-nickel alloy with contents of cobalt and nickel equal to or greater than that of copper, specifically a copper foil on the surface of the copper foil for bonding with the resin substrate of which 20 is provided an alloy fine roughening particle layer comprised of 5 to 12 mg/dm² copper, 6 to 13 mg/dm² cobalt, and 5 to 12 mg/dm² nickel, wherein the alloy fine roughening particle layer provided on the copper foil 25 surface may be treated for stainproof or may be treated by a silane coupling agent.